



12V P-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

V _{(BR)DSS}	R _{DS(ON) max}	I _{D MAX} T _A = +25°C
-12V	0.8 Ω @ V _{GS} = -4.5V	
	1.1 Ω @ V _{GS} = -2.5V	-0.2A
	3.0 Ω @ V _{GS} = -1.8V	-0.2A
	5.0 Ω @ V _{GS} = -1.5V	

Description

This MOSFET is designed to minimize the on-state resistance (R_{DS(ON)}) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

Applications

- Load Switch
- Power Management Functions
- Portable Power Adaptors

X2-DFN0806-3





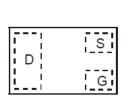
Bottom View

Features

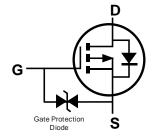
- 0.4mm Ultra Low Profile Package for Thin Application
- 0.48mm² Package Footprint, 16 Times Smaller than SOT23
- Low On-Resistance
- Low Input Capacitance
- ESD Protected Gate
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

Mechanical Data

- Case: X2-DFN0806-3
- Case Material: Molded Plastic, "Green" Molding Compound.
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish NiPdAu over Copper Leadframe. Solderable per MIL-STD-202, Method 208 @
- Weight: 0.00043 grams (Approximate)



Top View
Package Pin Configuration



Internal Schematic

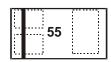
Ordering Information (Note 4)

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	Part Number	Case	Packaging
	DMP1555UFA-7B	X2-DFN0806-3	10,000/Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information



Top View Bar Denotes Gate and Source Side

55 = Product Type Marking Code



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	
Drain-Source Voltage	V _{DSS}	-12	V	
Gate-Source Voltage	V_{GSS}	±8	V	
Continuous Drain Current (V _{GS} = -4.5V)	(Note 5)	I _D	-0.2	Α
Pulsed Drain Current	(Note 6)	I _{DM}	-1.5	Α

Thermal Characteristics

Characteristic	Symbol	Value	Units	
Total Power Dissipation	(Note 5)	P_{D}	0.36	W
Thermal Resistance, Junction to Ambient	(Note 5)	$R_{ heta JA}$	353	°C/W
Operating and Storage Temperature Range	T _{J,} T _{STG}	-55 to 150	°C	

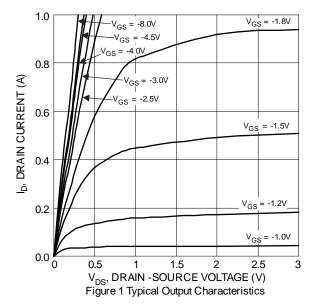
Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 7)							
Drain-Source Breakdown Voltage	BV _{DSS}	-12		_	V	$V_{GS} = 0V, I_{D} = -250\mu A$	
Zero Gate Voltage Drain Current T _J = +25°C	I _{DSS}	_	_	-1	μA	$V_{DS} = -10V, V_{GS} = 0V$	
Gate-Source Leakage		_	_	±10	μA	$V_{GS} = \pm 8V$, $V_{DS} = 0V$	
ON CHARACTERISTICS (Note 7)							
Gate Threshold Voltage	V _{GS(th)}	-0.4	_	-1.0	V	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	
		_	0.4	0.8	Ω	V _{GS} = -4.5V, I _D = -0.2A	
Static Drain-Source On-Resistance		_	0.55	1.1		V _{GS} = -2.5V, I _D = -0.1A	
Static Drain-Source On-Resistance	R _{DS (ON)}	_	0.75	3.0		V _{GS} = -1.8V, I _D = -0.05A	
		_	1.0	5.0		$V_{GS} = -1.5V, I_D = -0.01A$	
Diode Forward Voltage	V _{SD}	_	_	-1.2	V	$V_{GS} = 0V, I_{S} = -0.2A$	
DYNAMIC CHARACTERISTICS (Note 8)						•	
Input Capacitance	C _{iss}	_	55.4	_	pF		
Output Capacitance		_	14.7	_	pF	$V_{DS} = -10V, V_{GS} = 0V,$ f = 1MHz	
Reverse Transfer Capacitance	C _{rss}	_	11.9	_	pF	1 = 1101112	
Total Gate Charge (V _{GS} = 4.5V)	Qg	_	0.84	_	nC		
Gate-Source Charge	Q _{gs}	_	0.12	_	nC	$V_{DS} = -6V, V_{GS} = -4.5V,$ $-I_{D} = -0.2A$	
Gate-Drain Charge	Q _{gd}	_	0.23	_	nC	- ID = -0.2A	
Turn-On Delay Time	t _{D(on)}	_	16	_	ns		
Turn-On Rise Time	t _r	_	62	_	ns	$V_{DD} = -6V$, $V_{GS} = -4.5V$,	
Turn-Off Delay Time	t _{D(off)}	_	232	_	ns	$I_D = -0.2A$, $R_G = 6\Omega$	
Turn-Off Fall Time	t _f	_	186	_	ns		

Notes:

- 5. Device mounted on FR-4 PCB, with minimum recommended pad layout.
- 6. Device mounted on minimum recommended pad layout test board, 10µs pulse duty cycle = 1%.
- 7. Short duration pulse test used to minimize self-heating effect.
- 8. Guaranteed by design. Not subject to product testing.





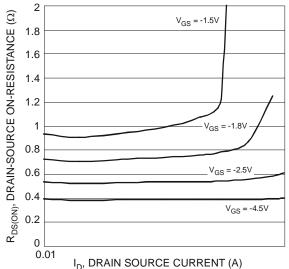
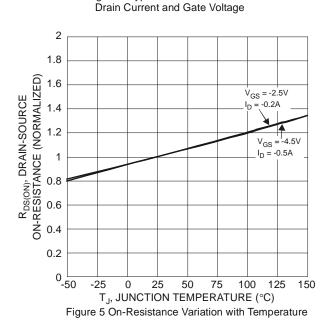
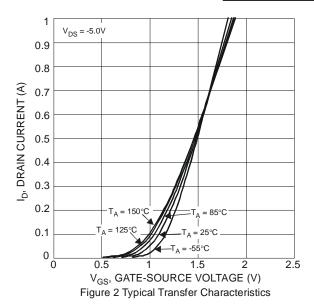
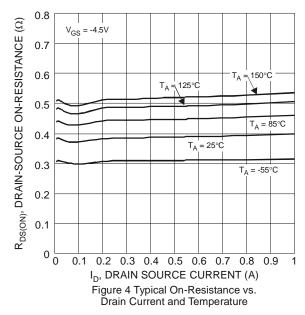


Figure 3 Typical On-Resistance vs.







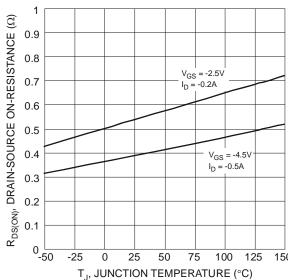


Figure 6 On-Resistance Variation with Temperature



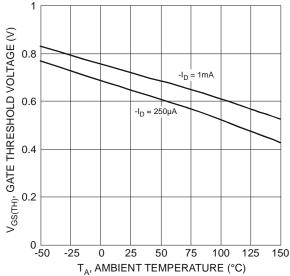
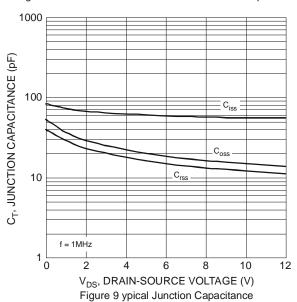
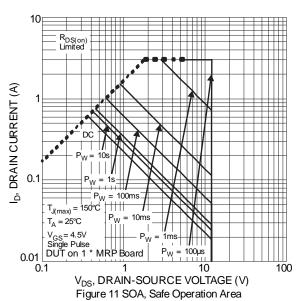
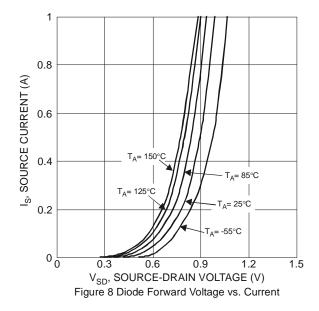
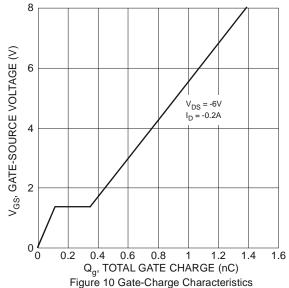


Figure 7 Gate Threshold Variation vs. Ambient Temperature

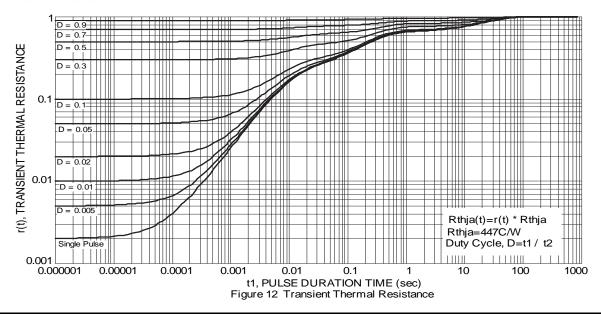






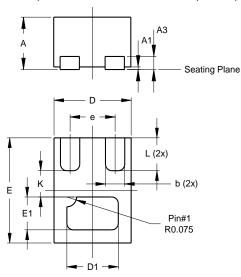






Package Outline Dimensions

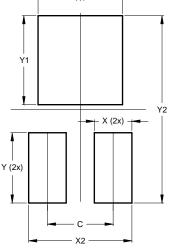
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.



X2-DFN0806-3					
Dim	Min	Max	Тур		
Α	0.375	0.40	0.39		
A1	0	0.05	0.02		
A3	-	-	0.10		
b	0.10	0.20	0.15		
D	0.55	0.65	0.60		
D1	0.35	0.45	0.40		
Е	0.75	0.85	0.80		
E1	0.20	0.30	0.25		
е	-	-	0.35		
K	-	-	0.20		
L	0.20	0.30	0.25		
All Dimensions in mm					

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)		
С	0.350		
Х	0.200		
X1	0.450		
X2	0.550		
Y	0.375		
Y1	0.475		
Y2	1.000		



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